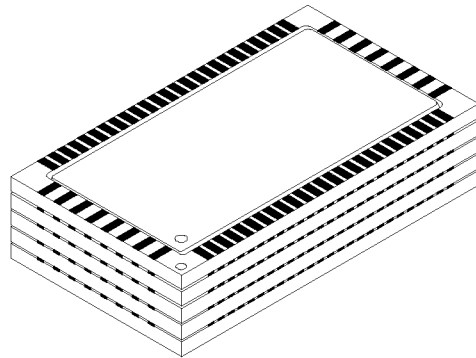


PRELIMINARY

DESCRIPTION:

The DPnnD8MX32RY5 is the 8 Meg x 32 Dynamic RAM module that utilize the new and innovative space saving TSOP stacking technology. The module is constructed of four 4 Meg x 16 Dynamic RAM's that are configured as 2 banks of 4 Meg x 32.

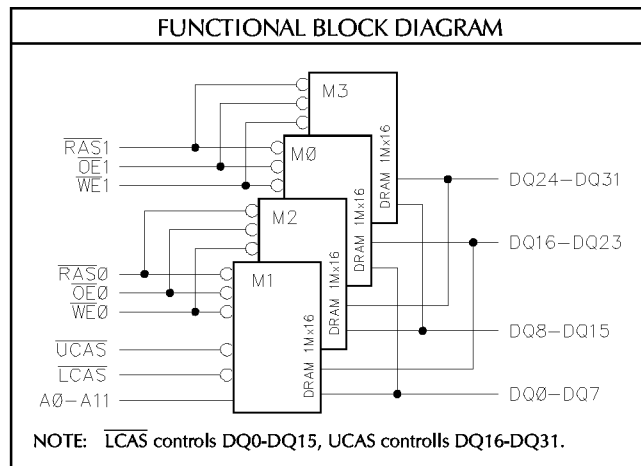
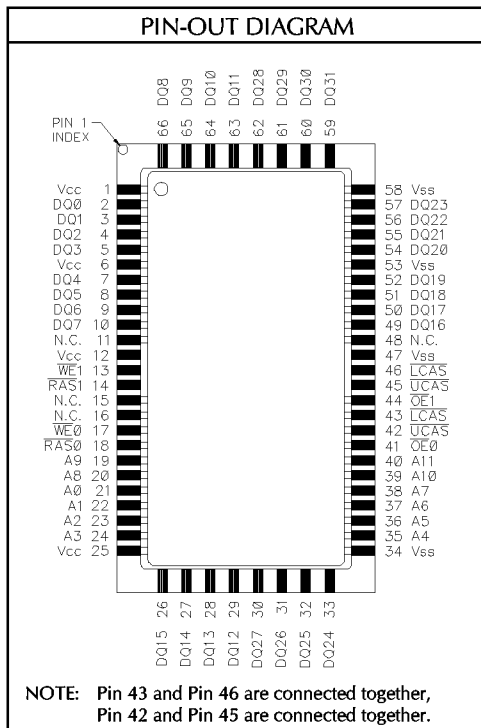
The DPnnD8MX32RY5 provides for a compatible upgrade path to lower density compatible modules. The module features high speed access times, common data inputs and outputs, and three standard refresh modes.



FEATURES:

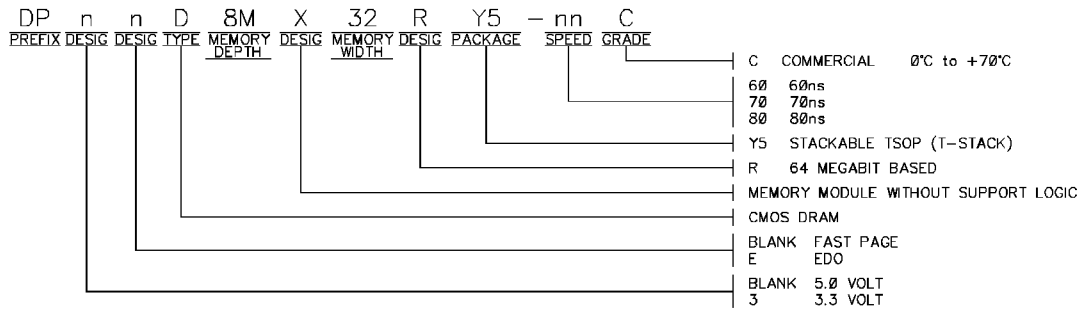
- Access Times: 60, 70, 80ns (max.)
- 5.0V or 3.3V Supply
- Common Data Inputs and Outputs
- EDO or Fast Page Mode Capability
- 4096 Cycles / 64 ms
- 3 Variations of Refresh:
 - $\overline{\text{RAS}}$ only Refresh
 - $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ Refresh
 - Hidden Refresh
- Package: TSOP Leadless Stack

PIN NAMES	
A0 - A11	Row Address: A0 - A11 Column Address: A0 - A9 Refresh Address: A0 - A11
DQ0 - DQ31	Data In / Data Out
$\overline{\text{UCAS}}$	Upper Column Address Strobe
$\overline{\text{LCAS}}$	Lower Column Address Strobe
$\overline{\text{RAS0}} - \overline{\text{RAS1}}$	Row Address Enables
$\overline{\text{WE0}} - \overline{\text{WE1}}$	Data Write Enables
$\overline{\text{OE0}} - \overline{\text{OE1}}$	Data Output Enables
VDD	Power Supply (+5V)
VSS	Ground
N.C.	No Connect

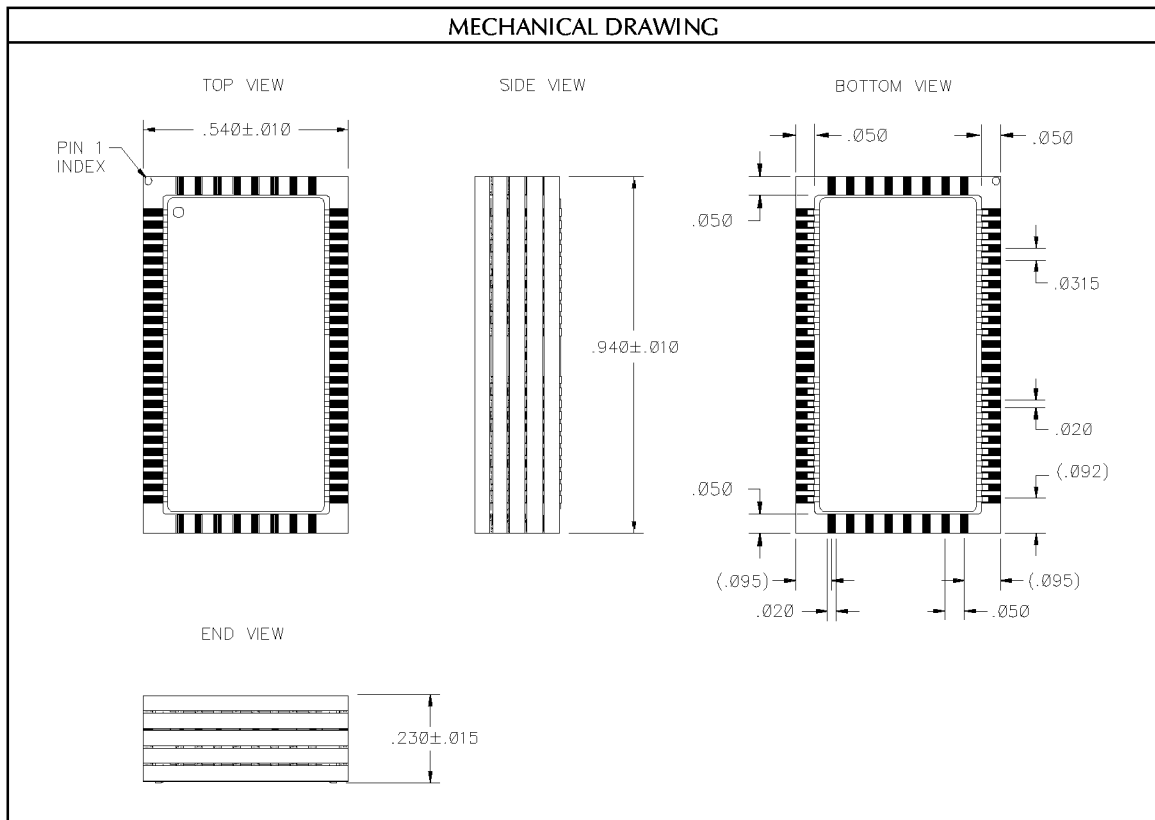


PRELIMINARY

ORDERING INFORMATION



MECHANICAL DRAWING



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 (714) 898-0007 (800) 642-4477 (Outside CA) ♦ FAX: (714) 897-1772 ♦ <http://www.dense-pac.com>